



Material Composition Declaration

EPC2044

Company Name	Efficient Power Conversion (EPC)	Issue Date:	2/24/2023
Contact Name:	Yanping Ma	Contact Title:	VP Quality
Contact Phone:	(310) 615-0280	Contact Email:	yanping.ma@epc-co.com
Part Weight:	3.7 mg	Type of Product:	eGaN FET

Construction Element	Substance	CAS No. If Applicable	Weight	Mass	Sum	Mass
			(mg)	(%)	(%)	(ppm)
Chip	Silicon	7440-21-3	3.1772	86.7289	89.7635	867289
	Silicon oxide	7631-86-9	0.0175	0.4783		4783
	Silicon nitride	12033-89-5	0.0071	0.1947		1947
	Gallium nitride	25617-97-4	0.0151	0.4125		4125
	Aluminum	7429-90-5	0.0306	0.8360		8360
	Aluminum nitride	24304-00-5	0.0034	0.0935		935
	Titanium	7440-32-6	0.0006	0.0164		164
	Titanium nitride	25583-20-4	0.0026	0.0722		722
	Copper	7440-50-8	0.0005	0.0140		140
	Tungsten	7440-33-7	0.0013	0.0343		343
	Polyimide		0.0323	0.8827		8827
Under Bump Metal	Titanium	7440-32-6	0.0004	0.0116	0.0577	116
	Copper	7440-50-8	0.0017	0.0461		461
Solder Bump	Copper	7440-50-8	0.2744	7.4911	10.1789	74911
	Tin	7440-31-5	0.0967	2.6394		26394
	Silver	7440-22-4	0.0018	0.0484		484
Sum in total:			3.6634	100.0000	100.0000	1000000

Note:

The substance content disclosed herewith is approximate and is based on engineering calculation. Statements are based on our present knowledge and may subject to change at any time due to technical requirements and development. EPC may update this document without notification. Statement may not include information regarding the minute quantities of dopant and metal materials in the electrical devices contained within the finished product.